

16545 09/690600
10/17/89

	Subclass
	Class
ISSUE CLASSIFICATION	

PATENT NUMBER

U.S. UTILITY Patent Application

<i>RJS</i>	O.I.P.E.	PATENT DATE	
SCANNED	<i>URZ</i>	Q.A.	<i>AA</i>

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/690600	D	257 029	780	2827 0729	<i>F.D.</i> <i>LUAN THAI</i>

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TITLE
 Solvent assisted burnishing of pre-underfilled solder bumped wafers for flipchip bonding

PTO-2040
 12/89

ISSUING CLASSIFICATION					
ORIGINAL		CROSS REFERENCE(S)			
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)		
INTERNATIONAL CLASSIFICATION					
<input type="checkbox"/> Continued on Issue Slip Inside File Jacket					

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	(Assistant Examiner) _____ (Date) _____			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent No. _____ _____ _____				ISSUE FEE	
<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.	(Primary Examiner) _____ (Date) _____ (Legal Instruments Examiner) _____ (Date) _____			Amount Due	Date Paid
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